



Compliance Declaration of RoHS Exemptions RoHS 排外條款宣告書

美麗微半導體股份有限公司特此宣告所有銷售之產品符合如下RoHS指令2011/65/EU之排外條款。

We hereby declare that our products comply with RoHS 2011/65/EU Exemption as below table.

	Exemption Item 排外條款項目	Use Part 使用部位
7(a)	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead). 高熔點錒錫中的鉛(例如鉛含量 $\geq 85\%$ 合金中的鉛)	Solder
7(c)-I	Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound. 含鉛之玻璃或陶瓷的電器和電子元件，介電陶瓷電容器除外例如高壓電子裝置，或玻璃或陶瓷基複合材料	GPP Dice & Glass Package

美麗微半導體股份有限公司
Formosa Microsemi Co., Ltd.



May., 1st ., 2022.